

# **iMAPS New England - 52nd Symposium & Expo**



**May 5, 2026**



**The Leading Regional Symposium Dedicated to  
Microelectronics, Assembly and Packaging**

**CALL FOR ABSTRACTS**

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Abstracts for Lecture & Interactive Poster Presentations  
on all aspects of Microelectronics Assembly & Packaging  
Special Focus on Advanced Materials, Advanced Packaging,  
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**Submission Deadline is December 15, 2025**



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